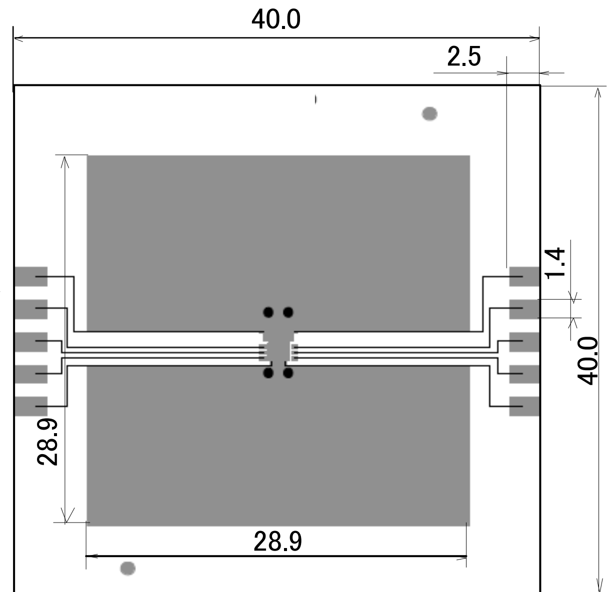
USP-9B01Power Dissipation

Power dissipation data for the USP-9B01 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 40mm×40mm (1600mm^2 in one side)
Copper (Cu) traces occupy 50% of the board area
in top and back faces
Material: Glass Epoxy (FR-4)
Thickness: 1.6mm
Through-hole: 4 x 0.8 Diameter



Evaluation Board (unit: mm)

2. Power Dissipation vs. Ambient temperature (85℃)

Board Mount (Tjmax = 125℃)

Ambient Temperature(℃)	Power Dissipation Pd (mW)	Thermal Resistance(℃/W)
25	1200	83.33
85	480